OXFORD INSTRUMENTS

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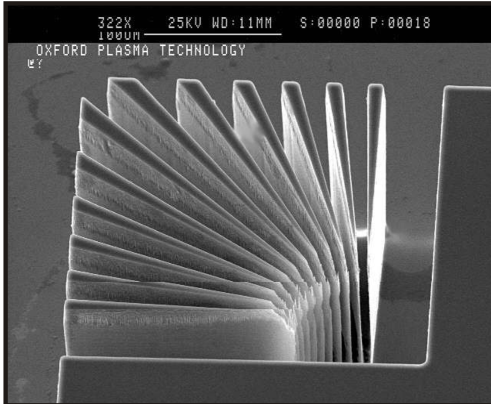
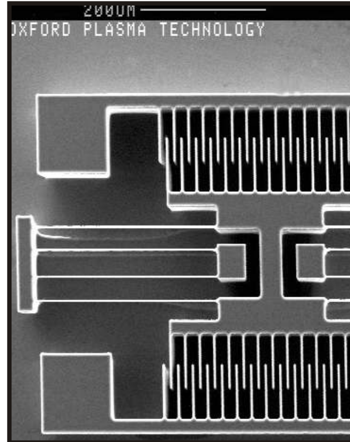
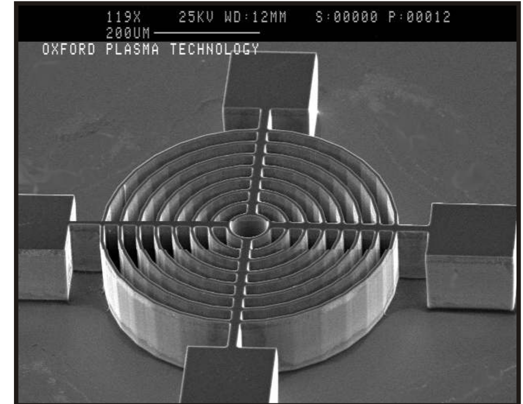
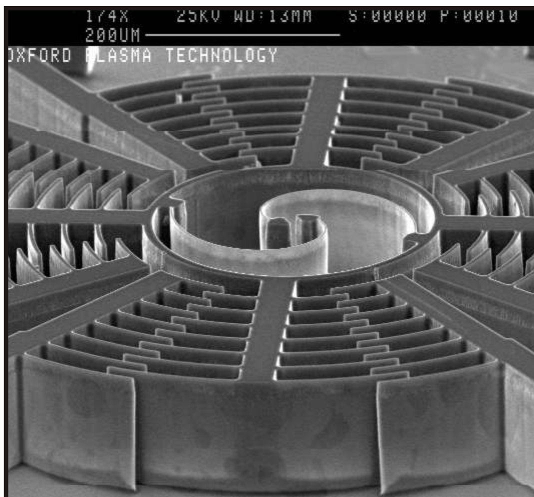
Plasmalab Data

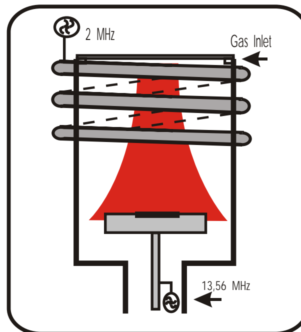
Si etching for MEMS

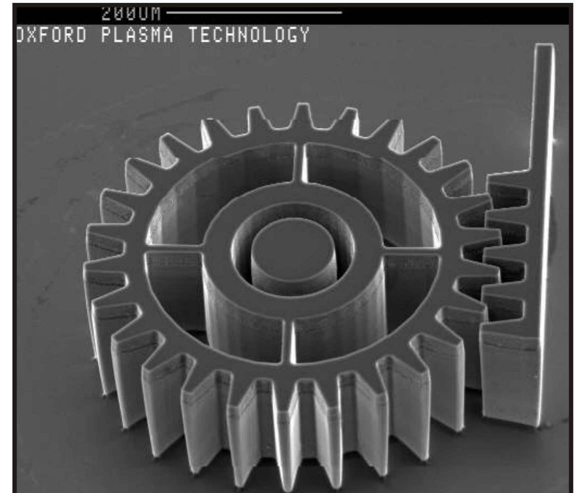












etched at the OPT application lab, Yatton (UK)

Technology:

Reactive Ion Etching
Inductive Coupled Plasma Source
room temperature process
“Bosch process”, gas chopping:
isotropic etch/ polymer formation
He backside cooling

Results:

Rate : up to 10 µm/min
Uniformity: $\leq \pm$ 2/ 3 % (4/ 6“)
anisotropic etch
aspect ratio up to 30 : 1
controllable wall profile
high selectivity to Resist (> 75:1)
and SiO_2(>> 100:1)

Plasmalab System 100